

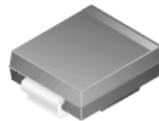


ES3A - ES3J

Fast Rectifiers

Features

- For surface mount applications.
- Glass passivated junction.
- Low profile package.
- Easy pick and place.
- Built-in strain relief.
- Superfast recovery times for high efficiency.



SMC/DO-214AB
Color Band Denotes Cathode

Absolute Maximum Ratings * T_a = 25°C unless otherwise noted

Symbol	Parameter	Value					Units
		ES3A	ES3B	ES3C	ES3D	ES3J	
V _{RRM}	Maximum Repetitive Reverse Voltage	50	100	150	200	600	V
I _{F(AV)}	Average Rectified Forward Current, .375" lead length @ T _A =75°C	3.0					A
I _{FSM}	Non-repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave	100					A
T _J , T _{STG}	Operating Junction and Storage Temperature Range	-50 to +150					°C
P _D	Power Dissipation	1.66					W

* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Thermal Characteristics

Symbol	Parameter	Value	Units
R _{θJA}	Thermal Resistance, Junction to Ambient *	47	°C/W
R _{θJL}	Thermal Resistance, Junction to Lead *	12	°C/W

* Device mounted on FR-4 PCB 0.013 mm.

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _F	Forward Voltage @ I _F = 3.0 A	0.95	1.7 V
T _{rr}	Reverse Recovery Time I _F = 0.5 A, I _R = 1.0 A, I _{RR} = 0.25 A	20	35 ns
I _R	Reverse Current @ rated V _R T _A = 25°C T _A = 100°C	10 500	uA
C _T	Total Capacitance V _R = 4.0 V, f = 1.0 MHz	45	pF

Typical Performance Characteristics

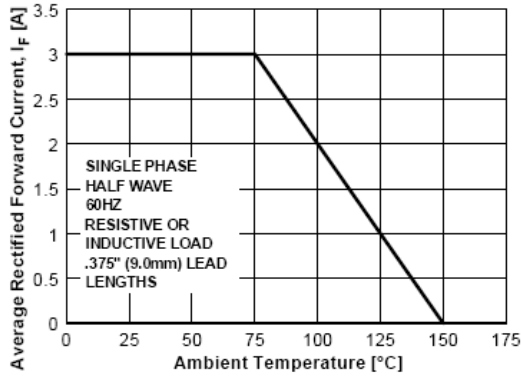


Figure 1. Forward Current Deration Curve

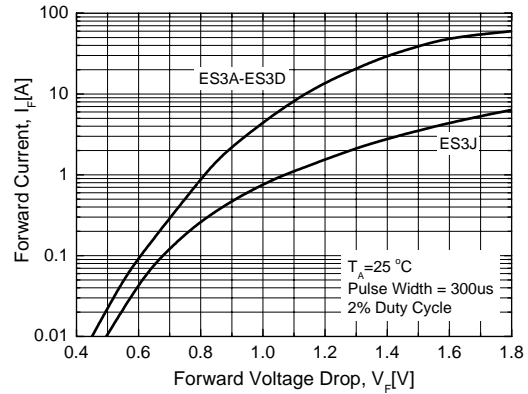


Figure 2. Forward Voltage Characteristics

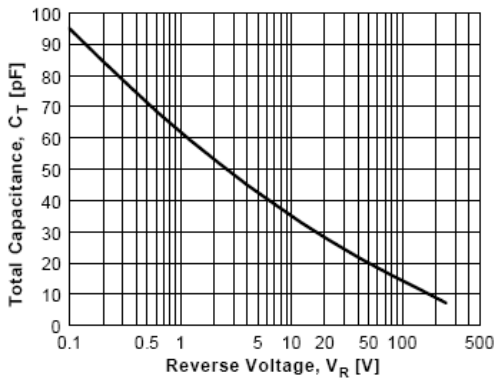


Figure 3. Total Capacitance

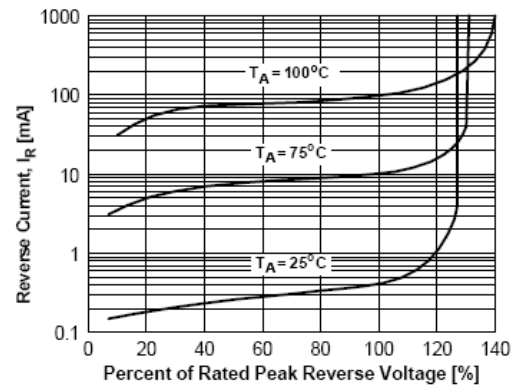
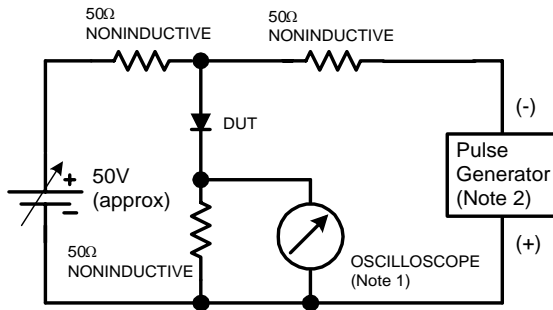
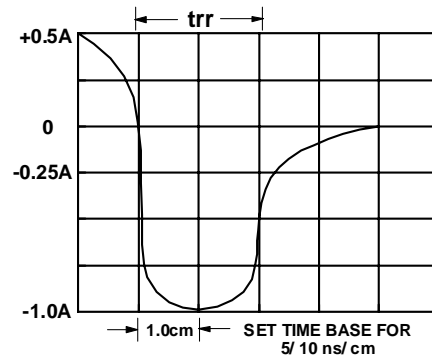


Figure 4. Reverse Current vs Reverse Voltage



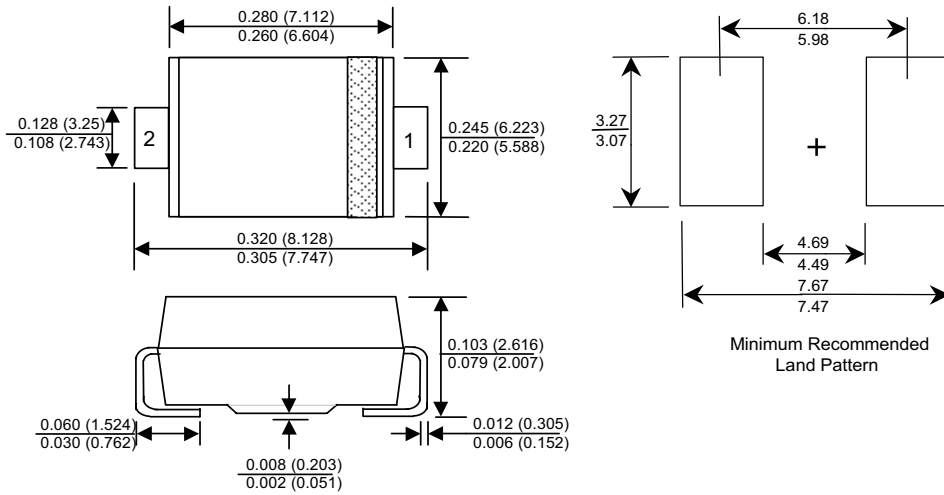
NOTES:

1. Rise time = 7.0 ns max; Input impedance = 1.0 megaohm 22 pf.
2. Rise time = 10 ns max; Source impedance = 50 ohms.



Package Dimensions

SMC / DO - 214AB



Dimensions in Inches(Millimeters)

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FASTr™	MicroPak™	QT Optoelectronics™	TinyPWM™	
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